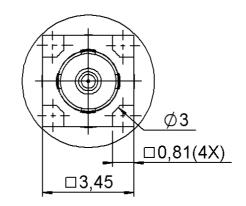
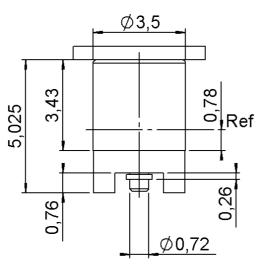
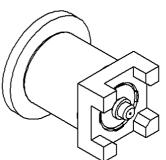
R110.427.810

REEL OF 500

Series : MMCX









Scale: 1/1

All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BRASS BERYLLIUM COPPER - PTFE	GOLD 0.2 OVER NICKEL 2 GOLD 1.3 OVER NICKEL 2 -

Issue: 0650 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



REEL OF 500

R110.427.810

Series: MMCX

PACKAGING

Standard	Unit	Other	
500	'W' option	Contact us	

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance 50 Ω

Frequency 0-6 GHz

VSWR 1.15 + 0,0500 x F(GHz) Maxi

Insertion loss TBD √F(GHz) dB Maxi

RF leakage - (- F(GHz)) dB Maxi Voltage rating 170 Veff Maxi

Dielectric withstanding voltage Insulation resistance 250 Veff mini $1000 \text{ M}\Omega$ mini

ENVIRONMENTAL

Operating temperature -55/+155 ° C

Hermetic seal **NA** Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

7 N mini
7 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **0,2260** g

Issue: 0650 B

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R110.427.810

REEL OF 500

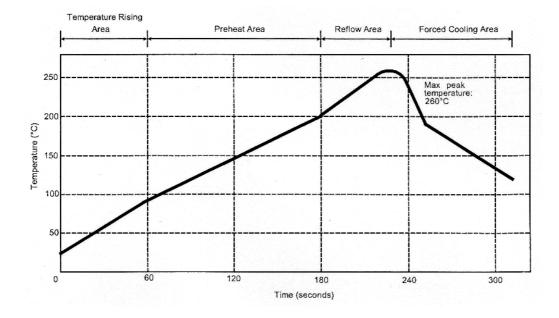
Series: MMCX

SOLDER PROCEDURE

- Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application.
 We recommend a low residue flux. We advise a thickness of 150 microms mini. (.006 inch mini).
 Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Aspiration port (see page 4) centered into body and push against it.
 A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. Soldering by infra-red reflow.

 Below please find ,the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



ParAmeter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

Issue: 0650 B

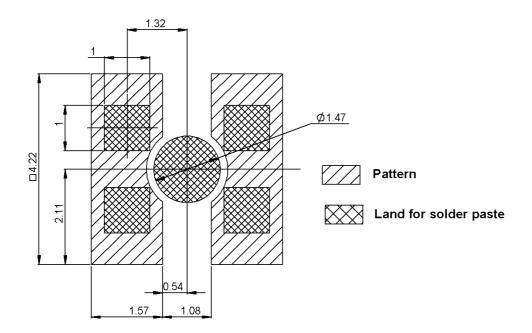
In the effort to improve our products, we reserve the right to make changes judged to be necessary.



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Series : MMCX

REEL OF 500



COPLANNAR LINE

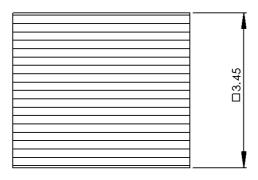
Pattern and Signal are on the same side

Thickness of PCB: .063"(1.6mm)

The material of PCB is the epoxy resin of glass fabrics bacs(Er=4.8)

The solder resist should be printed except for the land pattern on the PCB

SHADOW OF MMCX RECEPTACLE FOR VIDEO CAMERA



Issue: 0650 B

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